RELIABILITY REPORT

FOR

MAX4402AUA+

PLASTIC ENCAPSULATED DEVICES

September 27, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Manager, Reliability Engineering

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Conclusion

The MAX4402AUA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX4400-MAX4403 low-cost, general-purpose op amps offer rail-to-rail outputs, draw only 320µA of quiescent current, and operate from a single +2.5V to +5.5V supply. For additional power conservation, the MAX4401 offers a low-power shutdown mode that reduces supply current to 1µA (max) and puts the amplifier's output in a high-impedance state. These devices deliver ±1.4mA of output current and are unity-gain stable with a 1MHz gain-bandwidth product driving capacitive loads up to 400pF. The MAX4400-MAX4403 are specified to +125°C, making them suitable for use in a variety of harsh environments, such as automotive applications. The MAX4400 single amplifier is available in ultra-small 5-pin SC70 and space-saving 5-pin SOT23 packages. The single MAX4401 includes the shutdown feature and is available in a 6-pin SC70. The MAX4402 is a dual amplifier available in 8-pin SOT23 and SO packages. The MAX4403 quad amplifier is packaged in a 14-pin TSSOP or SO.

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II. Manufacturing Information

A. Description/Function:	Single/Dual/Quad, Low-Cost, Single-Supply, Rail-to-Rail Op Amps with Shutdown
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	April 22, 2000

III. Packaging Information

A. Package Type:	8-pin uMAX
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-2501-0097
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	221°C/W K.
Single Layer Theta Jc:	41.9°C/W
L. Multi Layer Theta Ja:	206.3°C/W
M. Multi Layer Theta Jc:	41.9°C/W

IV. Die Information

A. Dimensions:	67 X 24 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. B ackside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. I solation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. S ampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 160 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 6.9 \times 10^{-9}$

λ = 6.9 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD lot SOHAEQ002A D/C 0631, Latchup lot SOHAEQ001A D/C 0430)

The OX06 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

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Table 1
Reliability Evaluation Test Results

MAX4402AUA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80 0 80 0		IOHABQ001D, DC 0016 I0HADQ002F, DC 0136

Note 1: Life Test Data may represent plastic DIP qualification lots.

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